

# Declaration and Power of Attorney For Patent Application



專利申請聲明及委任狀

Chinese Language Declaration

如下所述發明者，我在此宣告：

我的地址、郵局地址和國籍身份都列在我的姓名下：

我相信我是原創的、第一個和單獨的發明者（若只列出一人姓名）或是原創的、第一個和共同的發明者（若列出一人以上姓名）。我要求的主題及申請的專利是關於發明\_\_\_\_\_

其說明書：

（註明一項）

隨同附上

於\_\_\_\_\_ 提出申請

申請順次號碼\_\_\_\_\_

於\_\_\_\_\_ 提出修正

（如適用於此）

發明者授權本申請案所委任的律師和代理人對簽署後的本協議書進行校核，並填入序號和申請日。

我在此陳述我已經再次查看並明瞭以上所指的說明書的內容，包括上述的要求及修正。

我，按照聯邦規則法典第三十七冊第一·五六條（甲）的條文，認知我提供與審查此申請書有關的重要資料的義務。

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ESD PROTECTION APPARATUS AND METHOD FOR DUAL-POLARITY INPUT PAD

the specification of which

(check one)

is attached hereto.

was filed on June 27, 2003 as

Application Serial No. 10/606,922

as amended on \_\_\_\_\_

(if applicable)

The Inventor(s) authorize(s) any attorneys and agents who have a power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

## Chinese Language Declaration

我，按照聯邦法典第三十五冊第一一九條的條文，  
依據下列外國專利申請書或發明者證明申請書在此  
要求受益優先權，並指出任何上述要求優先權所依  
據的外國專利申請書或發明者證明申請書其申請日  
在本申請書的申請日之前。

### 先前外國申請：

#### Prior Foreign Application(s)

			優先權要求 Priority Claimed	
012140160.8	P.R. China	1/7/2002	<input checked="" type="checkbox"/>	<input type="checkbox"/>
(號碼) (Number)	(國名) (Country)	(申請日/月/年) (Day/Month/Year Filed)	是 Yes	否 No
(號碼) (Number)	(國名) (Country)	(申請日/月/年) (Day/Month/Year Filed)	<input type="checkbox"/>	<input type="checkbox"/>
(號碼) (Number)	(國名) (Country)	(申請日/月/年) (Day/Month/Year Filed)	<input type="checkbox"/>	<input type="checkbox"/>

我，按照聯邦法典第三十五冊第一二〇條的條文，  
依據下列的美國申請書要求受益。至於其中每個要  
求的主題未曾依聯邦法典第三十五冊第一一二條的  
條文在先前的申請書中透露的，而發生在先前申請  
書的申請日和本申請書的國家或國際申請書的申請  
日之間的，我，依聯邦規則法典第三十七冊第一  
五六條（甲）的條文，認知提供重要資料的義務。

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

(申請順次號碼) (申請日期) (狀況)  
(已專利，申請中)

(Application Serial No.) (Filing Date) (status)  
(patented, pending, abandoned)

(申請順次號碼) (申請日期) (狀況)  
(已專利，申請中)

(Application Serial No.) (Filing Date) (status)  
(patented, pending, abandoned)

我在此聲明所有就我自己知識之下所做的一切陳述  
均屬真實的，而且依資料和信念所做的一切陳述也  
相信均是真實的。還有我了解，根據聯邦法典第  
十八冊第一〇〇一節的規定，有企圖不實或類似的聲  
明時，應受罰款或監禁的，或兩項同時的處分。像  
這些企圖不實的聲明會危害到本申請書的合法性或  
危害到任何專利的批准。

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

## Chinese Language Declaration

**委任狀：**

以列名發明者的身份，我在此指定下列律師和／或代理人以從事此申請及辦理與專利商標公署有關之事務：(列下姓名及登記號碼)

**Steven M. Rabin (Reg. No. 29,102)**  
**Robert H. Berdo, Jr. (Reg. No. 38,075)**

**POWER OF ATTORNEY:** As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: (list name and registration number)

**Thomas M. Champagne (Reg. No. 36,478)**  
**David S. Lee (Reg. No. 38,222)**

**通訊地址**

Send Correspondence to:

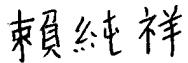
**RABIN & BERDO, P.C.**  
 1101 14th Street, N.W.  
 Washington, D.C. 20005

**電話 (姓名及電話號碼)**

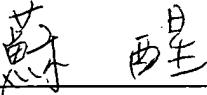
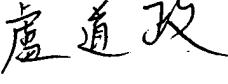
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第一個或獨有的發明者全名		<b>劉孟煌</b>	
發明者的簽名		日期	
		<b>Meng-Huang Liu</b>	
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第二個共同發明者全名 (若有)		Full name of second joint inventor, if any	
賴純祥		<b>Chun-Hsiang Lai</b>	
發明者的簽名		Second inventor's signature	
		<b>Chun-Hsiang Lai</b>	
地址		Residence <b>26-1, Lane 30, Sec. 2, Pei-Ping Rd., Taichung City, Taiwan R.O.C.</b>	
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郵局地址		Post Office Address <b>No. 16, Li-Shin Road, Science-Based Industrial Park, Hsinchu Taiwan R.O.C.</b>	
中華民國台灣省新竹市科學工業園區力行路16號			

## Chinese Language Declaration

第三個共同發明者全名 (若有) 蘇醒		Full name of third joint inventor, if any <b>Shin Su</b>
發明者的簽名 	日期	Inventor's signature <b>Shin Su</b> Date <b>June 23, 2003</b>
地址 中華民國台灣省台北縣板橋市後埔街58號4F	Residence <b>4Fl., No. 58, Houpu St., Banchiau City, Taipei, Taiwan R.O.C.</b>	
國籍 中華民國台灣	Citizenship <b>Taiwan R.O.C.</b>	
郵局地址 中華民國台灣省新竹市科學工業園區力行路16號	Post Office Address <b>No. 16, Li-Shin Road, Science-Based Industrial Park, Hsinchu Taiwan R.O.C.</b>	
第四個共同發明者全名 (若有) 盧道政		Full name of fourth joint inventor, if any <b>Tao-Cheng Lu</b>
發明者的簽名 	日期	Second inventor's signature <b>Tao Cheng Lu</b> Date <b>June 23, 2003</b>
住址 中華民國台灣省高雄市三民區嫩江街1巷36號	Residence <b>No.36, Lane 1, Nueh-Chiang St., San-Min district, Kaohsiung, Taiwan R.O.C.</b>	
國籍	Citizenship	
郵局住址 中華民國台灣省新竹市科學工業園區力行路16號	Post Office Address <b>No. 16, Li-Shin Road, Science-Based Industrial Park, Hsinchu Taiwan R.O.C.</b>	
第五個共同發明者全名 (若有)		Full name of fifth joint inventor, if any
發明者的簽名	日期	Inventor's signature Date
地址	Residence	
國籍	Citizenship	
郵局地址	Post Office Address	